



## Material Composition

**Product**      GS2972-IBE3  
**Package**      100L LBGA  
**Manufacturer**   Genum Corporation

**Date**      03/10/2008

Component	BOM	Weight of Component mg	Substance	Weight of Substance mg	Homogeneous material	
					%	ppm
Substrate	BT	159.840	SiO2	17.023	10.65	106500
			Acrylic	15.984	10.00	100000
			Epoxy	12.787	8.00	80000
			Bisphenol	23.976	15.00	150000
			Triazol	27.972	17.50	175000
			Cu	58.821	36.80	368000
			Ni	2.398	1.50	15000
			Au	0.879	0.55	5500
		Sub-total	159.840	100.00	1000000	
Mold Compound	KE-G1250	159.240	Silica (fused)	140.131	88	880000
			Epoxy resin	9.554	6	60000
			Phenolic resin	8.758	5.5	55000
			Carbon black	0.796	0.5	5000
			Sub-total	159.240	100.00	1000000
Chip 1		7.590	Si	7.491	98.7	987000
			Al	0.046	0.6	6000
			W	0.030	0.4	4000
			Ti	0.023	0.3	3000
			Sub-total	7.590	100.00	1000000
Chip 2		1.810	Si	1.786	98.7	987000
			Al	0.011	0.6	6000
			W	0.007	0.4	4000
			Ti	0.005	0.3	3000
			Sub-total	1.810	100.00	1000000
Die Attach	Ablestik 2100A	5.150	Ag	3.966	77	770000
			Epoxy Resin	0.335	6.5	65000
			Functionalized Resin	0.335	6.5	65000
			Diester	0.515	10	100000
			Sub-total	5.150	100.00	1000000
Wire	25_NL03F	3.690	Au	3.690	99.99	999900
Solder Balls	Senju	48.640	Sn	46.451	95.5	955000
			Ag	1.946	4	40000
			Cu	0.243	0.5	5000
			Sub-total	48.640	100.00	1000000
<b>Total</b>		385.960				

**GENNUM CORPORATION**

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